

March 2013

FGA25N120FTD 1200 V, 25 A Field Stop Trench IGBT

Features

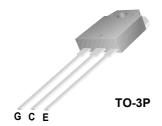
- Field Stop Trench Technology
- · High Speed Switching
- Low Saturation Voltage: $V_{CE(sat)} = 1.6 V @ I_C = 25 A$
- · High Input Impedance
- RoHS Complaint

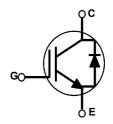
Applications

· Induction Heating, Microvewave Oven

General Description

Using advanced field stop trench technology, Fairchild®s 1200V trench IGBTs offer superior conduction and switching performances for soft switching applications. The device can operate in parallel configuration with exceptional avalanche ruggedness. This device is designed for induction heating and microwave oven.





Absolute Maximum Ratings

Symbol	Description		Ratings	Unit
V _{CES}	Collector to Emitter Voltage		1200	V
V _{GES}	Gate to Emitter Voltage		± 25	V
I _C	Collector Current	@ T _C = 25°C	50	A
.0	Collector Current	@ T _C = 100°C	25	A
I _{CM (1)}	Pulsed Collector Current		75	Α
I _F	Diode continuous Forward current	@ T _C = 100°C	25	Α
P _D	Maximum Power Dissipation	@ $T_C = 25^{\circ}C$	313	W
ט י	Maximum Power Dissipation	$@T_{C} = 100^{\circ}C$	125	W
$T_{\rm J}$	Operating Junction Temperature		-55 to +150	°C
T _{stg}	Storage Temperature Range		-55 to +150	°C
TL	Maximum Lead Temp. for soldering Purposes, 1/8" from case for 5 seconds		300	°C

Notes:

1: Repetitiverating: Pulse width limited by max. junction temperature

Thermal Characteristics

Symbol	Parameter	Тур.	Max.	Unit
$R_{\theta JC}(IGBT)$	Thermal Resistance, Junction to Case	-	0.4	°C/W
$R_{\theta JC}(Diode)$	Thermal Resistance, Junction to Case	-	1.42	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	-	40	°C/W

Package Marking and Ordering Information

			Packaging		Max Qty
Device Marking	Device	Package	Type	Qty per Tube	per Box
FGA25N120FTD	FGA25N120FTDTU	TO-3PN	-	-	30

Electrical Characteristics of the IGBT T_C = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Unit
Off Charac	teristics					
BV _{CES}	Collector to Emitter Breakdown Voltage	$V_{GE} = 0V, I_{C} = 1mA$	1200	-	-	V
I _{CES}	Collector Cut-Off Current	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	1	mA
I _{GES}	G-E Leakage Current	V _{GE} = V _{GES} , V _{CE} = 0V	-	-	±250	nA
On Charac	teristics					
V _{GE(th)}	G-E Threshold Voltage	I_C = 25mA, V_{CE} = V_{GE}	3.5	6	7.5	V
` '		I _C = 25A, V _{GE} = 15V	-	1.6	2	V
V _{CE(sat)}	Collector to Emitter Saturation Voltage	I _C = 25A, V _{GE} = 15V, T _C = 125°C	-	1.88	-	V
Dynamic C	haracteristics	•			•	
C _{ies}	Input Capacitance		-	3830	-	pF
C _{oes}	Output Capacitance	V _{CE} = 30V _, V _{GE} = 0V, f = 1MHz	-	130	-	pF
C _{res}	Reverse Transfer Capacitance	- I - IIVITZ	-	86	-	pF
Switching	Characteristics		•	!	!	
t _{d(on)}	Turn-On Delay Time		-	48	-	ns
t _r	Rise Time	V_{CC} = 600V, I_{C} = 25A, R_{G} = 15 Ω , V_{GE} = 15V, Inductive Load, T_{C} = 25°C	-	96	-	ns
t _{d(off)}	Turn-Off Delay Time		-	210	-	ns
t _f	Fall Time		-	215	-	ns
E _{on}	Turn-On Switching Loss		-	0.34	-	mJ
E _{off}	Turn-Off Switching Loss		-	0.90	1.20	mJ
E _{ts}	Total Switching Loss		-	1.24	-	mJ
t _{d(on)}	Turn-On Delay Time		-	44	-	ns
t _r	Rise Time		-	113	-	ns
t _{d(off)}	Turn-Off Delay Time	V _{CC} = 600V, I _C = 25A,	-	232	-	ns
t _f	Fall Time	$R_G = 15\Omega$, $V_{GE} = 15V$,	-	390	-	ns
E _{on}	Turn-On Switching Loss	Inductive Load, T _C = 125°C	-	0.38	-	mJ
E _{off}	Turn-Off Switching Loss		-	1.39	-	mJ
E _{ts}	Total Switching Loss		-	1.77	-	mJ
Qg	Total Gate Charge		-	160	-	nC
Q _{ge}	Gate to Emitter Charge	V _{CE} = 600V, I _C = 25A, V _{GE} = 15V	-	30	-	nC
Q _{gc}	Gate to Collector Charge	VGE - 10V	-	78	-	nC

Electrical Characteristics of the Diode $T_C = 25^{\circ}C$ unless otherwise noted

Symbol	Parameter	Test Conditions		Min.	Тур.	Max	Unit
V _{FM}	Diode Forward Voltage	I _F = 25A	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	1.4	1.8	V
FIVI	2.000 r o.ma.u romago		$T_{\rm C} = 125^{\rm o}{\rm C}$	-	1.42	-	1 1
t _{rr}	Diode Reverse Recovery Time		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	770	-	ns
AII.	2.000 1.0.00 1.00010.) 1		$T_{\rm C}$ = 125°C	-	895	-	
I _{rr}	Diode Reverse Recovery Time	I _{ES} =25A, dI _{ES} /dt = 200A/μs	$T_{\rm C} = 25^{\rm o}{\rm C}$	-	48	-	Α
-11	2.000 1.010.00 1.000.01, 1		$T_{\rm C}$ = 125°C	-	50	-	, ,
Q _{rr}	Diode Reverse Recovery Charge		$T_{\rm C} = 25^{\rm o}{\rm C}$	-	18	-	μC
~ii	2.545 . to . 5.55 . to obvory officingo		$T_{\rm C}$ = 125°C	1	23	-	,,,

Figure 1. Typical Output Characteristics

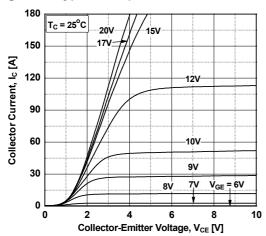


Figure 3. Typical Saturation Voltage Characteristics

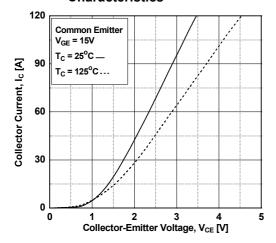


Figure 5. Saturation Voltage vs. Case
Temperature at Variant Current Level

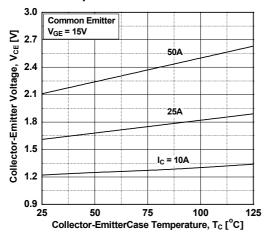


Figure 2. Typical Output Characteristics

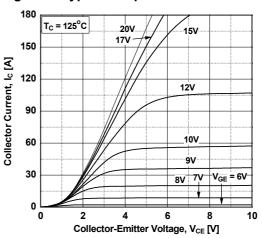


Figure 4. Transfer Characteristics

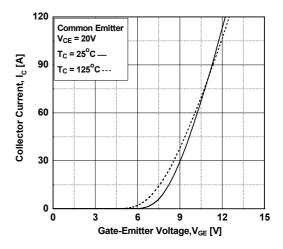


Figure 6. Saturation Voltage vs. V_{GE}

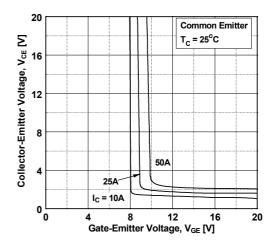


Figure 7. Saturation Voltage vs. V_{GE}

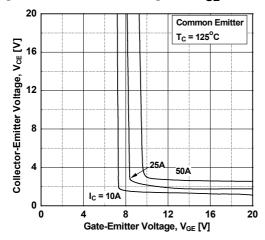


Figure 9. Gate charge Characteristics

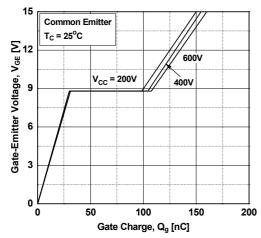


Figure 11. Turn-on Characteristics vs.
Gate Resistance

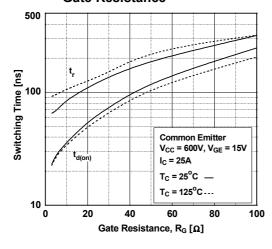


Figure 8. Capacitance Characteristics

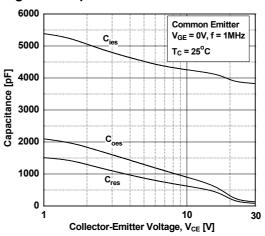


Figure 10. SOA Characteristics

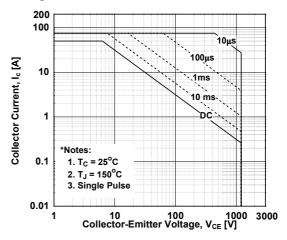


Figure 12. Turn-off Characteristics vs.
Gate Resistance

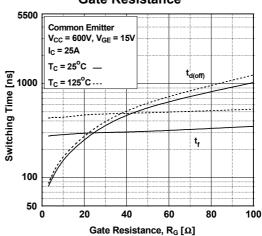


Figure 13. Turn-on Characteristics vs. **Collector Current**

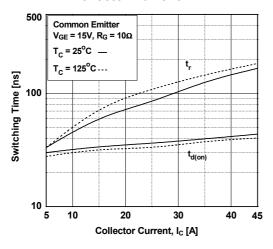


Figure 14. Turn-off Characteristics vs. **Collector Current**

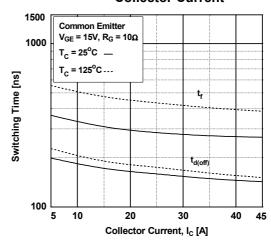


Figure 15. Switching Loss vs. Gate Resistance

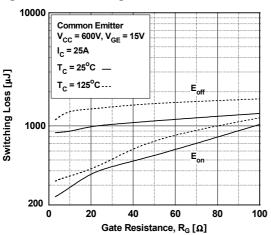


Figure 16. Switching Loss vs. Collector Current

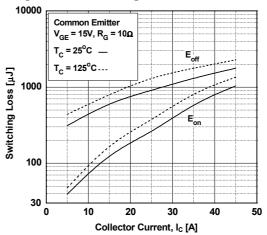
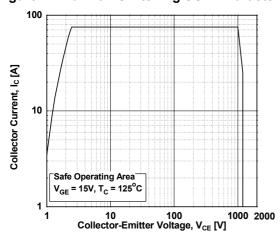


Figure 17. Turn off Switching SOA Characteristics Figure 18. Forward Characteristics



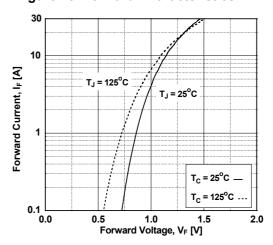


Figure 19. Reverse Recovery Current

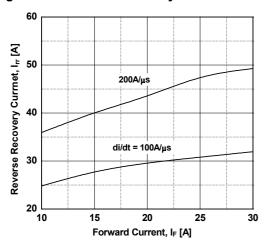


Figure 20. Stored Charge

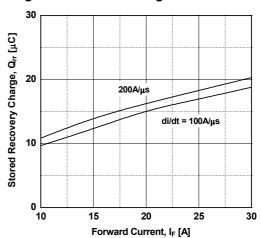
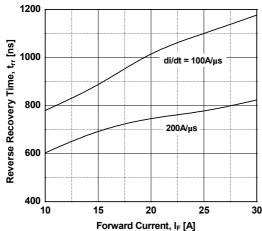
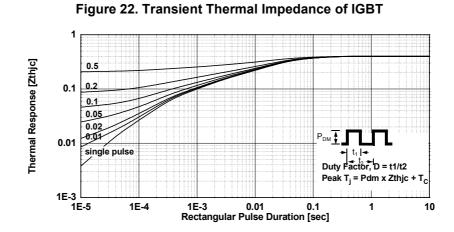


Figure 21. Reverse Recovery Time

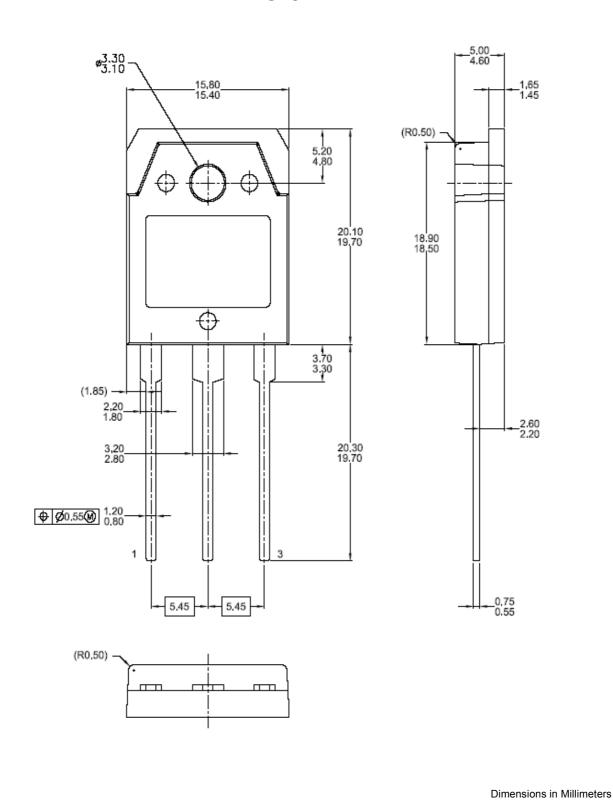


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Mechanical Dimensions

TO-3PN







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